A WAFER CARRIER ASSEMBLY FOR CHEM-MECH POLISHING

ABSTRACT

A wafer carrier assembly (104) including a subassembly (100) for in-situ nondestructive pad conditioning, characterized by continuously cleansing the pad surface (140) with an energized fluid. The fluid may be abrasive in nature, such as a slurry, or non-abrasive, such as DeIonized (DI) water. In addition, the fluid may be of a type known to assist in removing slurry and/or residual materials from a pad surface and followed by a DI water rinse. The chemical may be either liquid or gas.

Fig. 3